Product/Process Change Notice - PCN 09_0271 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: AD5541/2 and AD5551/2 Alternative Wafer Fab Process

Publication Date: 06-May-2010

Effectivity Date: 04-Aug-2010 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Bond wire size change and AD5541/2 specification improvements

Description Of Change

The 8" 0.6um BiCMOS (H6) wafer fab process at Analog Devices, Limerick, Ireland has been qualified as alternative wafer fab location for the AD5541/2 and AD5551/2 devices. These parts are currently fabed on the 6" 2um ABCMOS2 wafer fab process at Analog Devices, Wilmington, Massachusetts.

The purpose of this revision is to advise:

1) The change in wafer fab geometry, from 2um to 0.6um, has resulted in a reduction of bond pad size necessitating a change from 1.2mil to 1.0mil diameter gold wire.

2) The transfer to the 0.6um wafer fab process has also resulted in an improvement in AD5541/2 data sheet specifications as per attached file. (AD5551/2 data sheet changes have been previously communicated in PCN 10_0075).

Reason For Change

1)Wire diameter reduction required for reduced geometry.

2)Updating AD5541/2 datasheets to accurately reflect improved specifications.

Impact of the change (positive or negative) on fit, form, function & reliability

The form, fit, quality and reliability of the AD5541/2 and AD5551/2 are not affected by this change.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Reliability Report.

Supporting Documents

Attachment 1: Type: Datasheet Specification Comparison

ADI_PCN_09_0271_Rev_A_AD5541_AD5542_Specchanges.pdf

Attachment 2: Type: Reliability Report

ADI_PCN_09_0271_Rev_A_RQR05402A.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models					
Existing Parts - Product Family / Model Number (46)					
AD5541 / AD5541AR	AD5541 / AD5541AR-REEL7	AD5541 / AD5541ARZ	AD5541 / AD5541ARZ-REEL7	AD5541 / AD5541ARZ-U1	AD5541 / AD5541BR
AD5541 / AD5541BRZ	AD5541 / AD5541BRZ-U1	AD5541 / AD5541CR	AD5541 / AD5541CRZ	AD5541 / AD5541CRZ-REEL7	AD5541 / AD5541CRZ-U1
AD5541 / AD5541JR	AD5541 / AD5541JR-REEL7	AD5541 / AD5541JRZ	AD5541 / AD5541JRZ-REEL7	AD5541 / AD5541LR	AD5541 / AD5541LR-REEL7
AD5541 / AD5541LRZ	AD5541 / AD5541LRZ-REEL7	AD5541 / AD5542CRZ-U1	AD5542 / AD5542AR	AD5542 / AD5542AR-REEL7	AD5542 / AD5542ARZ
AD5542 / AD5542ARZ-REEL7	AD5542 / AD5542BR	AD5542 / AD5542BR-REEL7	AD5542 / AD5542BRZ	AD5542 / AD5542BRZ-REEL7	AD5542 / AD5542CR
AD5542 / AD5542CR-REEL7	AD5542 / AD5542CRZ	AD5542 / AD5542CRZ-REEL7	AD5542 / AD5542JR	AD5542 / AD5542JR-REEL7	AD5542 / AD5542JRZ
AD5542 / AD5542JRZ-REEL7	AD5542 / AD5542LR	AD5542 / AD5542LRZ	AD5551 / AD5551BR	AD5551 / AD5551BR-REEL7	AD5551 / AD5551BRZ
AD5551 / AD5551BRZ-REEL7	AD5552 / AD5552BR	AD5552 / AD5552BR-REEL7	AD5552 / AD5552BRZ		

Appendix B - Revision History		
Rev	**Publish Date**	**Rev Description**
Rev. -	20-Apr-2010	Initial Release
Rev. A	06-May-2010	Bond wire size change and AD5541/2 specification improvements